

	Application No.	Applicant(s)	
Notice of Allowability	10/708,426	CHEN ET AL.	
	Examiner	Art Unit	
	Chuong A Luu	2825	
The MAILING DATE of this communication applied allowable, PROSECUTION ON THE MERITS herewith (or previously mailed), a Notice of Allowance (PTOLNOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT of the Office or upon petition by the applicant. See 37 CFR 1.	IS (OR REMAINS) CLOSED in 85) or other appropriate common RIGHTS. This application is s	n this application. If not inclu unication will be mailed in du	ided ie course. <b>THIS</b>
1. This communication is responsive to <u>March 22, 2005.</u>			
2. ☑ The allowed claim(s) is/are <u>1-4 and 6</u> .			•
3. 🗵 The drawings filed on 02 March 2004 are accepted by t	he Examiner.		
<ul> <li>4. Acknowledgment is made of a claim for foreign priority a) All b) Some* c) None of the: <ol> <li>Certified copies of the priority documents h</li> <li>Certified copies of the priority documents h</li> <li>Copies of the certified copies of the priority International Bureau (PCT Rule 17.2(a)).</li> </ol> </li> <li>* Certified copies not received: <ol> <li>Applicant has THREE MONTHS FROM THE "MAILING DAT noted below. Failure to timely comply will result in ABANDO</li> </ol> </li> </ul>	ave been received.  ave been received in Application  documents have been received  E" of this communication to file	on No d in this national stage applic	
THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.  5. A SUBSTITUTE OATH OR DECLARATION must be su INFORMAL PATENT APPLICATION (PTO-152) which is	bmitted. Note the attached EXA		NOTICE OF
6. CORRECTED DRAWINGS ( as "replacement sheets") r  (a) including changes required by the Notice of Draftsp  1) hereto or 2) to Paper No./Mail Date  (b) including changes required by the attached Examin Paper No./Mail Date  Identifying indicia such as the application number (see 37 CF each sheet. Replacement sheet(s) should be labeled as such  7. DEPOSIT OF and/or INFORMATION about the deattached Examiner's comment regarding REQUIREMENT.	nust be submitted. Person's Patent Drawing Review Per's Amendment / Comment or R 1.84(c)) should be written on the the header according to 37 CF Posit of BIOLOGICAL MATI	w ( PTO-948) attached r in the Office action of the drawings in the front (not to the first in t	
Attachment(s)  1. ☑ Notice of References Cited (PTO-892)  2. ☑ Notice of Draftperson's Patent Drawing Review (PTO-94)  3. ☑ Information Disclosure Statements (PTO-1449 or PTO/S Paper No./Mail Date  4. ☑ Examiner's Comment Regarding Requirement for Deposor of Biological Material	8) 6. ☐ Interview Si Paper No./ B/08), 7. ☒ Examiner's	formal Patent Application (P ummary (PTO-413), /Mail Date Amendment/Comment Statement of Reasons for A	,

## **DETAILED ACTION**

## **EXAMINER'S AMENDMENT**

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

The application has been amended as follows:

# To the Specification

In the March 22, 2005 amendment to the specification entered in the IFW of this application, after "10/248,750" insert –now U.S. Patent 6,873,057—

#### Remarks

This amendment updates the status of the parent application. The applicant's representative is reminded to update the status of the parent via an amendment. In this way the status change of the parent will not be missed upon allowance.

## Allowable Subject Matter

Claims 1-4 and 6 are allowed.

The following is an examiner's statement of reasons for allowance: The examiner has reviewed the prior art in light of applicant's claimed invention and finds that the claims define over the prior art. The cited prior art does not disclose or suggest the combined limitation of a process to form a stacked semiconductor device inter alia the

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limitations "... depositing a dielectric layer over the semiconductor wafer, the dielectric layer having a main surface and a damascene recess on the main surface; depositing a copper layer in the damascened recess and to fill the damascened recess; performing a chemical mechanical polishing process to polish the copper layer such that the copper layer has an exposed upper surface substantially co-planar with the main surface of the dielectric layer; capping the exposed upper surface with a bi-layer capping film consisting of a lower HDPCVD silicon nitride layer and an upper oxygen doped silicon carbide layer...."

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Chuong A Luu whose telephone number is (571) 272-1902. The examiner can normally be reached on M-F (6:30-3:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

CAL March 31, 2005

David Nelms Supervisory Patent Examiner Technology Center 2800 Page 4